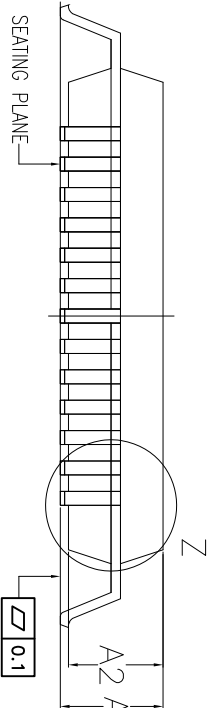
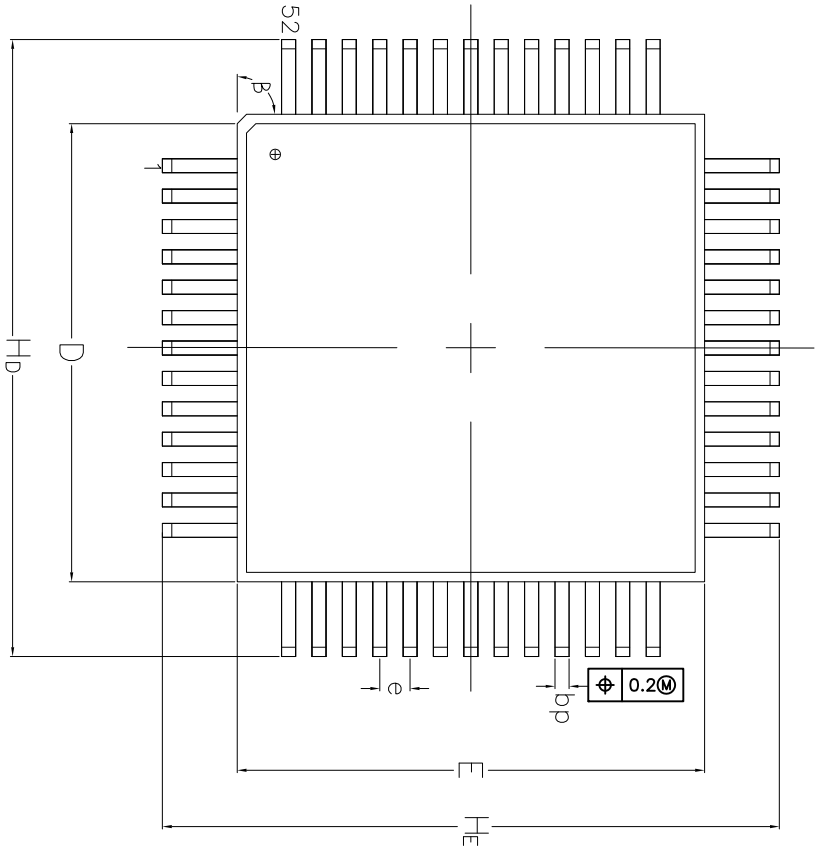


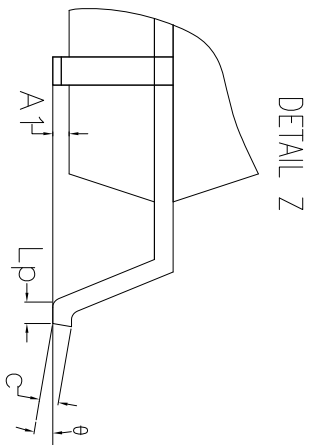
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	2/22/16	JHUA




- 2. WEIGHT <math>< 0.6 \text{ g}</math>
- 3. PACKAGE BODY MATERIAL LOW STRESS EPOXY
- 4. LEAD MATERIAL Cu-ALLOY
- 5. LEAD FINISH SOLDER PLATING
- 6. LEAD FORM Z-BENDS

DIMENSION OF SUB-GROUP B1	
$e_{nom}$	0.65
$A_{max}$	2.35
$b_{min}$	0.22
$b_{pmx}$	0.38
$H_{min}$	12.95
$H_{max}$	13.45
$H_{pmn}$	12.95
$L_{pmn}$	0.73

DIMENSION OF SUB-GROUP C1	
$A_{min}$	2.05
$A1 \text{ min}$	0.10
$A1 \text{ max}$	0.25
$A2 \text{ min}$	1.95
$A2 \text{ max}$	2.10
$C \text{ min}$	0.13
$C \text{ max}$	0.23
$D_{min}$	9.90
$D_{max}$	10.10
$E_{min}$	9.90
$E \text{ max}$	10.10
$\theta_{min}$	$0^\circ$
$\theta_{max}$	$10^\circ$
$B$	$45^\circ$



TOLERANCES UNLESS SPECIFIED	DECIMAL	ANGULAR
XXXX±		
XXXX±		
APPROVALS	DATE	
DRAWN $\partial\partial\partial\partial$	2/22/16	
CHECKED		
 <b>www.IDT.com</b>		
6024 Silver Creek Valley Rd San Jose, CA 95138 PHONE: (408) 727-6116 FAX: (408) 492-8674		
TITLE DBG52 PACKAGE OUTLINE DRAWN 10.0 x 10.0 mm BODY 0.65 mm PITCH PQFP		
SIZE	DRAWING No.	REV
C	PSC-4644	00
DO NOT SCALE DRAWING		SHEET 1 OF 1